12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20190506000.1
Add Cu as Alternative Wire Base Metal for Selected Device(s)
Change Notification / Sample Request

Date: February 17, 2020

Dear TI Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

The customer should acknowledge receipt of this notification by email within **30** days of the date of receipt. Lack of acknowledgement of this notice within 30 days constitutes customer acceptance of the change.

Samples or additional data to support customer evaluation must be requested within 30 days of receipt of this notification. If samples are requested for evaluation the customer must provide evaluation results within the sample evaluation period indicated on page 3 of this notification. The Sample Evaluation Period begins on the date the customer receives samples from TI.

If the customer approved the change TI can proceed with implementation of the change. The proposed first ship date is shown on page 3.

If the customer does not approve the PCN or the approval response is not provided within the Sample Evaluation Period, TI can implement the change, but the customer may elect to place an order for unchanged product by the Last Time Buy Date for delivery by the Last Time Ship Date. TI cannot guarantee that shipments to the customer after any last time order is delivered will not include the changed material. If the customer places an order with delivery after the Last Time Shipment Date, the order may be fulfilled with changed material or any material processed to TI specifications at that future time.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your field sales representative.

Sincerely,
PCN Team
SC Business Services

20190506000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM5035CSQX/NOPB	39110875
LM5035CSQ/NOPB	39111148
LM5035CSQX/NOPB	39111148
DS125DF111SQ	43130033
DS125DF111SQE	43130033
LMK04031BISQX/S7002381	46040042
LM5101ASD-1/NOPB	99010TRL
DS125DF111SQ	99011EXU
UCC21520ADWR	99011RXY

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190506000.1	**PCN Date:**	Feb 17, 2020
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)		
Proposed 1st Ship Date:	May 17, 2020	**Sample Eval Period:**	90 days
Last Time Buy Date:	Jul. 16, 2019	**Last Time Ship Date:**	Oct. 14, 2020

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of new assembly material set to add Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

Material	Current	Proposed
Wire	Au	Cu

Note: Devices highlighted in Yellow will continue to use Au wire for Die to Die bonding

Reason for Change:

Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change.

Changes to product identification resulting from this PCN:

None.

Product Affected:

UCC21520ADWR	LMK04031BISQX/S7002381	LM5101ASD-1/NOPB
DS125DF111SQ	LM5035CSQ/NOPB	
DS125DF111SQE	LM5035CSQX/NOPB	

Qualification Report

Approved on 23-Sep-2014

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DP83848TSQ	Qual Device: DS91M040TSQAW	Qual Device: DS100DX410EL16	Qual Device: DS80PCI402A2TT	Qual Device: LMH0366SQENOPB	Qual Device: LMH0394SQ/NOPB
PC	PreCon Level 1	Level 1-260C					3/720/0	
PC	PreCon Level 2	Level 2-260C	3/1079/0		-	3/720/0	-	-
PC	PreCon Level 3	Level 3-260C	-	1/255/0	3/720/0	-	-	3/231/0
HAST	Biased HAST, 130C/85%RH	96/hrs. @130C	-	-	-	-	-	3/231/0
AC	Autoclave 121C	96HRS	3/231/0	1/77/0	3/231/0	3/231/0	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	unHAST-96 HRS/-	3/231/0	1/77/0	3/231/0	3/231/0	3/231/0	-
TC	Temperature Cycle, -65/150C	TMCL500X	3/231/0	1/77/0	3/231/0	3/231/0	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 hrs. @170C	3/231/0	-	-	3/231/0	-	-
ED	Side By Side Electrical Characterization.	Per Datasheet Parameters	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass	Pass	Pass
MSL	Thermal Path Integrity	Level 2-260C	3/30/0	1/22/0	3/66/0	3/66/0	3/66/0	-
DPA	Destructive Physical Analysis Post 500 Temp Cycle	x-section and de process to examine assembly robustness, Check for stich bond and bond pad integrity	3/3/0	-	3/15/0	3/15/0	3/15/0	1/5/0 Post 96 hours HAST
YLD	FTY and Bin Summary	Compare against baseline	Pass	Pass	Pass	Pass	Pass	Pass

- QBS: Qual By Similarity
- Qual Device DS100DX410EL16 is qualified at LEVEL3-260C
- Qual Device DS80PCI402A2TT is qualified at LEVEL2-260C
- Qual Device LMH0366SQENOPB is qualified at LEVEL1-260C
- Qual Device LMH0394SQ/NOPB is qualified at -
- Qual Device LMH0394SQ/NOPB REV A is qualified at LEVEL3-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

Qualification Report
Approved on 27-Dec-2018

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UCC21520QDWR
AC	Autoclave 121C	96 Hours	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/77/0
HTOL	Life Test, 125C	1000 Hours	1/77/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0

- Qual Device UCC21520QDWR is qualified at LEVEL2-260C
- Device UCC21520QDWR contains multiple dies.
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

Qualification Report
Approved on 25-Apr-2019

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMX2581ESQJTYY	Qual Device: LP3971SQ2GZ85K
HAST	Biased HAST, 110C/85%RH	264 Hours	3/231/0	3/231/0
HAST	Biased HAST, 110C/85%RH	528 Hours (for info only)	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0

Type	Test Name / Condition	Duration	Qual Device: LMX2581ESQJTYY	Qual Device: LP3971SQ2GZ85K
UHAST	Unbiased HAST 110C/85%RH	264 Hours	-	3/231/0
WBP	Bond Pull	Wires	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0

- Qual Device LMX2581ESQJTYY is qualified at LEVEL3-260CG
- Qual Device LP3971SQ2GZ85K is qualified at LEVEL1-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

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